

REMARKS

The Official Action mailed May 27, 2005, has been received and its contents carefully noted. This response is filed within three months of the mailing date of the Official Action and therefore is believed to be timely without extension of time. Accordingly, the Applicants respectfully submit that this response is being timely filed.

The Applicants note with appreciation the consideration of the Information Disclosure Statements filed on February 10, 2003, December 10, 2003, March 19, 2004, and August 10, 2004. A further Information Disclosure Statement is submitted herewith and consideration of this Information Disclosure Statement is respectfully requested.

Claims 1-41 were pending in the present application prior to the above amendment. Claims 1-3 and 13 have been amended to better recite the features of the present invention, and new claims 50-67 have been added to recite additional protection to which the Applicants are entitled. Accordingly, claims 1-41 and 50-67 are now pending in the present application, of which claims 1-6, 12-14, 50 and 51 are independent. For the reasons set forth in detail below, all claims are believed to be in condition for allowance. Favorable reconsideration is requested.

In response to the request in the Official Action, the Abstract has been amended such that it is limited to a single paragraph. Reconsideration and withdrawal of the objection is respectfully requested.

In response to the request in the Official Action, claim 13 has been amended to correct a minor informality in that "conductive film" has been changed to "conductive barrier film." Reconsideration and withdrawal of the objection is respectfully requested.

The Official Action rejects claims 1-14 and 28-41 as anticipated by U.S. Patent Application Publication No. 2003/0127649 to Chae. The Official Action rejects claims 3, 4, 6, 8, 9, 10, 11, 13, 14-32, 35, 36, 38, 40 and 41 as obvious based on the combination of Chae and U.S. Patent Application Publication No. 2005/0014359 to Segawa et al.

In order to overcome these rejections, a verified English translation of priority application JP 2002-276295 filed September 20, 2002, will be filed as soon as it is complete and received from Japan. Since Chae has a filing date of December 16, 2002, which is later than the filing date of JP 2002-276295, the Applicants respectfully submit that the rejections under §§ 102 and 103 should be overcome.

The Official Action provisionally rejects claims 1-41 under the doctrine of obviousness-type double patenting over claims 1-17 of copending Application No. 10/659,585. In response, the Applicants respectfully request that the double patenting rejections be held in abeyance until an indication of allowable subject matter is made in either the present application or the copending application. At such time, the Applicants will respond to any remaining double patenting rejections.

New claims 50-67 have been added to recite additional protection to which the Applicants are entitled. The features of claims 57-67 are supported, for example, by Figures 12A-12C and Embodiment Mode 5. For the reasons stated above and already of record, the Applicants respectfully submit that new claims 50-67 are in condition for allowance.

Should the Examiner believe that anything further would be desirable to place this application in better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number listed below.

Respectfully submitted,


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